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HEEWON SEO .

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Korean Patent Bar Korean Bar U.S. State Bar

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24 October 2003

Darryl Mexic, Esq. Sughrue, Mion, PLLC 2100 Pennsylvania Avenue, N.W. Washington, D.C 20037-3213 U.S.A.

VIA COURIER

Your Ref.: Q62787

Our Ref.: SH-RECEIVED

U.S. Patent Application No. 09/801,060 Re:

Samsung Electronics Co., Ltd.

OCT 3 1 2003

Technology Center 2600

Dear Mr. Mexic:

In connection with the above-identified application, please be informed that five references were cited in the Search Report dated 27 June 2003 of the European Patent Application No. 01301730.6 which corresponds to the above U.S. application. Thus, we enclose herewith copies of the search report together with copies of the cited references.

To meet the duty of disclosure, please take the necessary steps for submitting an Information Disclosure Statement in due course.

We appreciate your cooperation in this case.

Sincerely yours,

Y.P. LEE, MOCK & PARTNERS

Youngpil Lee

YPL/jja Enclosure